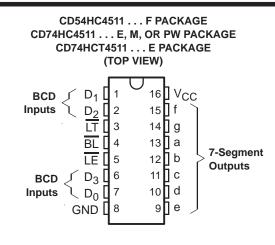
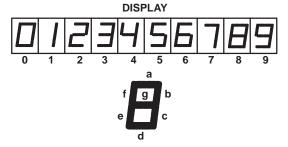
SCHS279D - DECEMBER 1998 - REVISED OCTOBER 2003

- 2-V to 6-V V<sub>CC</sub> Operation ('HC4511)
- 4.5-V to 5.5-V V<sub>CC</sub> Operation (CD74HCT4511)
- High-Output Sourcing Capability
  - 7.5 mA at 4.5 V (CD74HCT4511)
  - 10 mA at 6 V ('HC4511)
- Input Latches for BCD Code Storage
- Lamp Test and Blanking Capability
- Balanced Propagation Delays and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- 'HC4511
  - High Noise Immunity,
     N<sub>IL</sub> or N<sub>IH</sub> = 30% of V<sub>CC</sub> at V<sub>CC</sub> = 5 V
- CD74HCT4511
  - Direct LSTTL Input Logic Compatibility,
     V<sub>IL</sub> = 0.8 V Maximum, V<sub>IH</sub> = 2 V Minimum
  - CMOS Input Compatibility, I  $_{I} \leq$  1  $\mu A$  at VOL, VOH





#### description/ordering information

The CD54HC4511, CD74HC4511, and CD74HCT4511 are BCD-to-7 segment latch/decoder/drivers with four address inputs ( $D_0$ – $D_3$ ), an active-low blanking ( $\overline{BL}$ ) input, lamp-test ( $\overline{LT}$ ) input, and a latch-enable ( $\overline{LE}$ ) input that, when high, enables the latches to store the BCD inputs. When  $\overline{LE}$  is low, the latches are disabled, making the outputs transparent to the BCD inputs.

These devices have standard-size output transistors, but are capable of sourcing (at standard  $V_{OH}$  levels) up to 7.5 mA at 4.5 V. The HC types can supply up to 10 mA at 6 V.

#### ORDERING INFORMATION

TA	PACK	AGET	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	DDID E	T. b ( 05	CD74HC4511E	CD74HC4511E
	PDIP – E	Tube of 25	CD74HCT4511E	CD74HCT4511E
		Tube of 40	CD74HC4511M	
5500 1- 40500	SOIC - M	Reel of 2500	CD74HC4511M96	HC4511M
–55°C to 125°C		Reel of 250	CD74HC4511MT	
	TOOOD DW	Reel of 2000	CD74HC4511PWR	1114544
	TSSOP – PW	Reel of 250	CD74HC4511PWT	HJ4511
	CDIP – F	Tube of 25	CD54HC4511F3A	CD54HC4511F3A

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCHS279D - DECEMBER 1998 - REVISED OCTOBER 2003

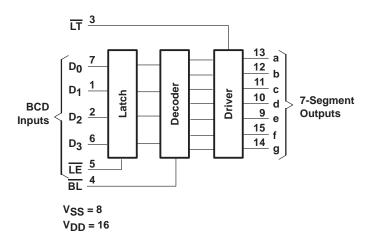
#### **FUNCTION TABLE**

		11	NPUT	S						0	UTPL	JTS		
LE	BL	LT	D <sub>3</sub>	D <sub>2</sub>	D <sub>1</sub>	D <sub>0</sub>	а	b	С	d	е	f	g	DISPLAY
Х	Χ	L	Х	Χ	Х	Χ	Н	Н	Н	Н	Н	Н	Н	8
Х	L	Н	Х	Χ	Χ	Χ	L	L	L	L	L	L	L	Blank
L	Н	Н	L	L	L	L	Н	Н	Н	Н	Н	Н	L	0
L	Н	Н	L	L	L	Н	L	Н	Н	L	L	L	L	1
L	Н	Н	L	L	Н	L	Н	Н	L	Н	Н	L	Н	2
L	Н	Н	L	L	Н	Н	Н	Н	Н	Н	L	L	Н	3
L	Н	Н	L	Н	L	L	L	Н	Н	L	L	Н	Н	4
L	Н	Н	L	Н	L	Н	Н	L	Н	Н	L	Н	Н	5
L	Н	Н	L	Н	Н	L	L	L	Н	Н	Н	Н	Н	6
L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	L	L	L	7
L	Н	Н	Н	L	L	L	Н	Н	Н	Н	Н	Н	Н	8
L	Н	Н	Н	L	L	Н	Н	Н	Н	L	L	Н	Н	9
L	Н	Н	Н	L	Н	L	L	L	L	L	L	L	L	Blank
L	Н	Н	Н	L	Н	Н	L	L	L	L	L	L	L	Blank
L	Н	Н	Н	Н	L	L	L	L	L	L	L	L	L	Blank
L	Н	Н	Н	Н	L	Н	L	L	L	L	L	L	L	Blank
L	Н	Н	Н	Н	Н	L	L	L	L	L	L	L	L	Blank
L	Н	Н	Н	Н	Н	Н	L	L	L	L	L	L	L	Blank
Н	Н	Н	Χ	Χ	Χ	Χ	†	†	†	†	†	†	†	†

X = Don't care

NOTE: Display is blank for all illegal input codes (BCD > HLLH).

# function diagram



<sup>†</sup> Depends on BCD code previously applied when  $\overline{LE} = L$ 

# logic diagram Latch LE D Latch LE Latch D Latch LE LE LE LE

SCHS279D - DECEMBER 1998 - REVISED OCTOBER 2003

# absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub> –0.5 V to 7
Input diode current, $I_{IK}$ ( $V_I < -0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}$ ) (see Note 1) $\pm 20 \text{ m}$
Output diode current, $I_{OK}$ ( $V_O < -0.5 \text{ V}$ or $V_O > V_{CC} + 0.5 \text{V}$ ) (see Note 1) $\pm 20 \text{ m}$
Continuous output source or sink current per output, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) $\pm 25$ m.
Continuous current through V <sub>CC</sub> or GND ±50 m.
Package thermal impedance, $\theta_{JA}$ (see Note 2): E package 67°C/N
M package 73°C/\
PW package 108°C/\
Lead temperature (during soldering):
At distance $1/16 \pm 1/32$ in $(1.59 \pm 0.79 \text{ mm})$ from case for 10 s maximum
Unit inserted into a PC board (minimum thickness 1/16 in, 1.59 mm),
with solder contacting lead tips only
Storage temperature, T <sub>stq</sub> –65 to 150°c

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The package thermal impedance is calculated in accordance with JESD 51-7.

#### recommended operating conditions for 'HC4511 (see Note 3)

			T <sub>A</sub> =	25°C	T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
Vcc	Supply voltage		2	6	2	6	2	6	V
		V <sub>CC</sub> = 2 V	1.5		1.5		1.5		
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15		3.15		3.15		V
		VCC = 6 V	4.2		4.2		4.2		
		V <sub>CC</sub> = 2 V		0.5		0.5		0.5	
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V		1.35		1.35		1.35	V
		V <sub>CC</sub> = 6 V		1.8		1.8		1.8	
VI	Input voltage		0	VCC	0	VCC	0	VCC	V
Vo	Output voltage		0	VCC	0	VCC	0	VCC	V
		V <sub>CC</sub> = 2 V		1000		1000		1000	
t <sub>t</sub>	Input transition (rise and fall) time	V <sub>CC</sub> = 4.5 V		500		500		500	ns
		VCC = 6 V		400		400		400	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SCHS279D - DECEMBER 1998 - REVISED OCTOBER 2003

### recommended operating conditions for CD74HCT4511 (see Note 4)

		T <sub>A</sub> = 1	25°C		T <sub>A</sub> = −55°C TO 125°C		T <sub>A</sub> = −40°C TO 85°C	
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		8.0		0.8		0.8	V
٧ <sub>I</sub>	Input voltage		VCC		VCC		VCC	V
VO	Output voltage		VCC		VCC		VCC	V
tt	Input transition (rise and fall) time		500		500		500	ns

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

'HC4511 electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	NDITIONS	VCC	T <sub>A</sub> = 25°C		T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	
			2 V	1.9		1.9		1.9		
		I <sub>OH</sub> = -20 μA	4.5 V	4.4		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9		5.9		5.9		V
		$I_{OH} = -7.5 \text{ mA}$	4.5 V	3.98		3.7		3.84		
		$I_{OH} = -10 \text{ mA}$	6 V	5.48		5.2		5.34		
			2 V		0.1		0.1		0.1	
		$I_{OL} = 20 \mu\text{A}$	4.5 V		0.1		0.1		0.1	
VOL	VI = VIH or VIL		6 V		0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$	4.5 V		0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0	_	6 V		±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V		8		160		80	μΑ
Ci		•			10		10		10	pF

SCHS279D - DECEMBER 1998 - REVISED OCTOBER 2003

#### CD74HCT4511

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	Vcc	T <sub>A</sub> = 25°C			T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT	
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V	Mr. Marsan Mar	I <sub>OH</sub> = -20 μA	45.77	4.4			4.4		4.4		V
VOH	$V_I = V_{IH}$ or $V_{IL}$	$I_{OH} = -4 \text{ mA}$	4.5 V	3.98			3.7		3.84		V
V	Mr. Marsan Mar	Ι <sub>Ο</sub> L = 20 μΑ	45.77			0.1		0.1		0.1	.,
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OL} = 4 \text{ mA}$	4.5 V			0.26		0.4		0.33	V
lį	$V_I = V_{CC}$ to GND		5.5 V			±0.1		±1		±1	μΑ
Icc	$V_I = V_{CC}$ or 0,	IO = 0	5.5 V			8		160		80	μΑ
∆l <sub>CC</sub> †	One input at V <sub>CC</sub> – Other inputs at 0 or		4.5 V to 5.5 V		100	360		490		450	μА
Ci						10		10		10	pF

 $<sup>^{\</sup>dagger}$  Additional quiescent supply current per input pin, TTL inputs high, 1 unit load. For dual-supply systems, theoretical worst-case (V<sub>I</sub> = 2.4 V, V<sub>CC</sub> = 5.5 V) specification is 1.8 mA.

#### **HCT INPUT LOADING TABLE**

INPUT	UNIT LOADS‡
LT, LE	1.5
BL, Dn	0.3

<sup>‡</sup> Unit load is  $\Delta I_{CC}$  limit specified in electrical characteristics table, e.g., 360  $\mu A$  maximum at 25°C

# 'HC4511 timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		Vcc	T <sub>A</sub> = 25°C		T <sub>A</sub> = -55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
		2 V	80		120		100		
t <sub>w</sub>	Pulse duration, LE low	4.5 V	16		24		20		ns
		6 V	14		20		17		
		2 V	60		90		75		
tsu	Setup time, BCD inputs before LE↑	4.5 V	12		18		15		ns
		6 V	10		15		13		
		2 V	3		3		3		
th	Hold time, BCD inputs before LE↑	4.5 V	3		3		3		ns
		6 V	3		3		3		

#### 'HC4511

# switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO	LOAD	VCC	T,	4 = 25°C	;	T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
				2 V			300		450		375	
	-	O tom t	C <sub>L</sub> = 50 pF	4.5 V			60		90		75	
	D <sub>n</sub>	Output		6 V			51		77		64	
			C <sub>L</sub> = 15 pF	5 V		25						
				2 V			270		405		340	
	<u>LE</u>	O . stan . st	$C_L = 50 pF$	4.5 V			54		81		68	
		Output		6 V			46		69		58	
tod			C <sub>L</sub> = 15 pF	5 V		23					nc	
<sup>t</sup> pd				2 V			220		330		275	ns
	BL	0	C <sub>L</sub> = 50 pF	4.5 V			44		66		55	
	BL	Output		6 V			37		56		47	
			C <sub>L</sub> = 15 pF	5 V		18						
				2 V			160		240		200	
	ĪŦ	O . stan . st	C <sub>L</sub> = 50 pF	4.5 V			32		48		40	
	LI	Output		6 V			27		41		34	
			C <sub>L</sub> = 15 pF	5 V		13						
				2 V			75		110		95	
t <sub>t</sub>		Any	C <sub>L</sub> = 50 pF	4.5 V			15		22		19	ns
				6 V			13		19		16	

SCHS279D - DECEMBER 1998 - REVISED OCTOBER 2003

#### CD74HCT4511

timing requirements over recommended operating free-air temperature range  $V_{CC}$  = 4.5 V (unless otherwise noted) (see Figure 2)

		T <sub>A</sub> = 25°C		T <sub>A</sub> = −55°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>W</sub>	Pulse duration, LE low	16		24		20		ns
t <sub>su</sub>	Setup time, BCD inputs before LE↑	16		24		20		ns
th	Hold time, BCD inputs before LE↑	5		5		5		ns

#### CD74HCT4511

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

PARAMETER	FROM	TO	LOAD	VCC	T <sub>A</sub> = 25°C			T <sub>A</sub> = -		T <sub>A</sub> = -		UNIT
	(INPUT)	(OUTPUT)	CAPACITANCE		MIN	TYP	MAX	MIN	MAX	MIN	MAX	
	2	Output	C <sub>L</sub> = 50 pF	4.5 V			60		90		75	
	D <sub>n</sub>	Output	C <sub>L</sub> = 15 pF	5 V		25						
	LE	Output	C <sub>L</sub> = 50 pF	4.5 V			54		81		68	
	LE	Output	$C_L = 15  pF$	5 V		23						
<sup>t</sup> pd	BL	O. den. d	$C_{L} = 50 \text{ pF}$	4.5 V			44		66		55	ns
	BL	Output	C <sub>L</sub> = 15 pF	5 V		18						
	ĪŢ	Output	C <sub>L</sub> = 50 pF	4.5 V			33		50		41	
	LI	Output	C <sub>L</sub> = 15 pF	5 V		13						
t <sub>t</sub>		Any	C <sub>L</sub> = 50 pF	4.5 V			15		22		19	ns

# operating characteristics, V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C

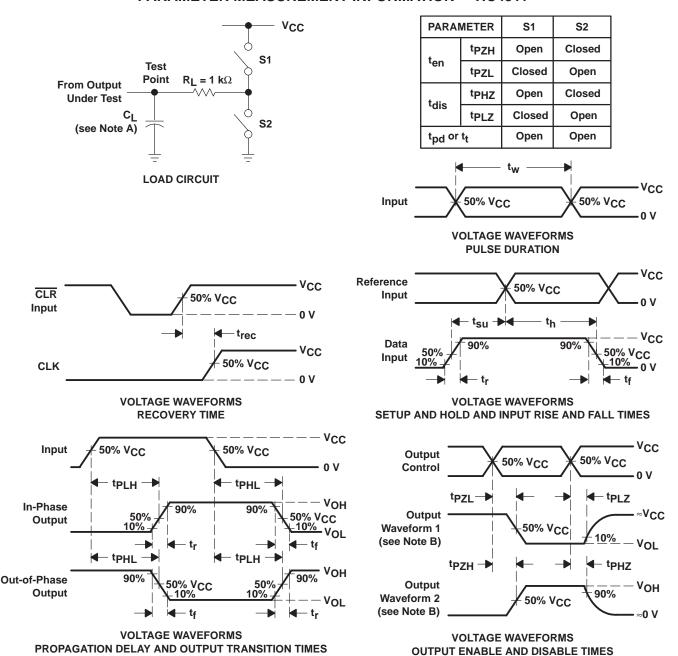
	PARAMETER		TYP	UNIT
c <sub>pd</sub> †	Decrease distribution consections as	'HC4511	114	
	Power dissipation capacitance	CD74HCT4511	110	pF

†  $C_{pd}$  is used to determine the dynamic power consumption, per package.  $P_D = C_{pd} \ V_C c^2 \ f_i + \Sigma \ C_L \ V_C c^2 \ f_0$  where:  $f_i$  = input frequency  $f_0$  = output frequency  $C_L$  = output load capacitance

 $V_{CC}$  = supply voltage



#### PARAMETER MEASUREMENT INFORMATION - 'HC4511

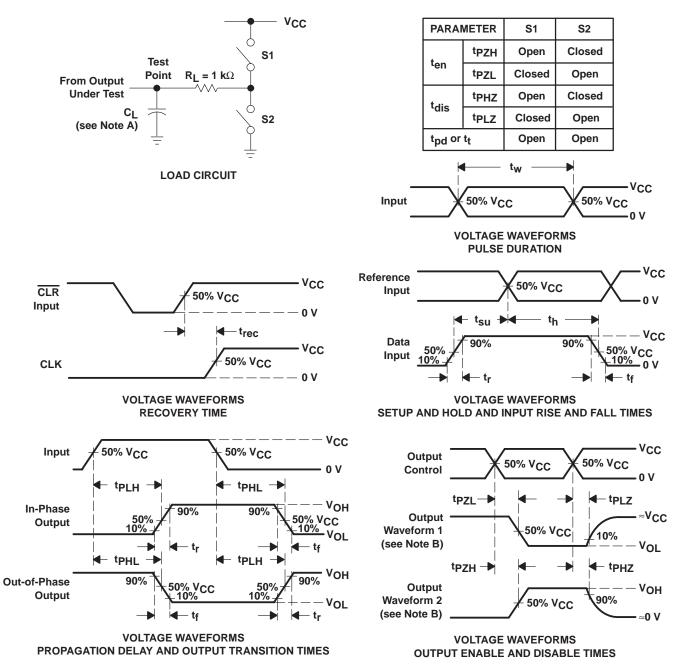


- NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .
  - D. For clock inputs, f<sub>max</sub> is measured with the input duty cycle at 50%.
  - E. The outputs are measured one at a time with one input transition per measurement.
  - F. tpLz and tpHz are the same as tdis.
  - G. tpzL and tpzH are the same as ten.
  - H. tpl H and tpHI are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



#### PARAMETER MEASUREMENT INFORMATION - CD74HCT4511



- NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \Omega$ ,  $t_f = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .
  - D. For clock inputs,  $f_{\text{max}}$  is measured with the input duty cycle at 50%.
  - E. The outputs are measured one at a time with one input transition per measurement.
  - F. tpLz and tpHz are the same as tdis.
  - G. tpzL and tpzH are the same as ten.
  - H. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



7-Sep-2021 www.ti.com

#### **PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8773301EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8773301EA CD54HC4511F3A	Samples
CD54HC4511F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8773301EA CD54HC4511F3A	Samples
CD74HC4511E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4511E	Samples
CD74HC4511EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4511E	Samples
CD74HC4511M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4511M	Samples
CD74HC4511M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4511M	Samples
CD74HC4511M96E4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4511M	Samples
CD74HC4511MG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4511M	Samples
CD74HC4511MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4511M	Samples
CD74HC4511PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4511	Samples
CD74HC4511PWRE4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4511	Samples
CD74HC4511PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4511	Samples
CD74HC4511PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4511	Samples
CD74HC4511PWTE4	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4511	Samples
CD74HCT4511E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4511E	Samples
CD74HCT4511EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4511E	Samples

<sup>(1)</sup> The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design. PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

### PACKAGE OPTION ADDENDUM

www.ti.com 7-Sep-2021

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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#### OTHER QUALIFIED VERSIONS OF CD54HC4511, CD74HC4511:

Catalog: CD74HC4511

Military: CD54HC4511

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

www.ti.com 27-Jul-2021

### TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device Device	_	Package		SPQ	Reel	Reel	A0	B0	K0	P1 .	W	Pin1
	Type	Drawing			Diameter (mm)	Width W1 (mm)	(mm)	(mm)	(mm)	(mm)	(mm)	Quadrant
CD74HC4511M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4511PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4511PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 27-Jul-2021



\*All dimensions are nominal

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Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
CD74HC4511M96	SOIC	D	16	2500	340.5	336.1	32.0	
CD74HC4511PWR	TSSOP	PW	16	2000	853.0	449.0	35.0	
CD74HC4511PWT	TSSOP	PW	16	250	853.0	449.0	35.0	

# D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

# PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



#### 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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